

Abstract of the Disclosure

A semiconductor device includes projecting electrodes formed on one surface of a wiring substrate so as to have a prescribed height, a semiconductor chip having a thickness smaller than the height of the projecting electrodes, and an electronic component having a thickness larger than that of the semiconductor chip and mounted on the other surface of the wiring substrate so that the wiring substrate is warped to be recessed at the one surface. Thus, the rigidity as well as the spacing between the semiconductor chip and the mounting board are assured. Moreover, the semiconductor device having a logic LSI mounted on both surfaces of a wiring substrate is mounted on a mounting board in a housing with projecting electrodes having a prescribed height interposed therebetween, wherein the wiring substrate is warped to be recessed on the side having the projecting electrodes.